



N-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	Q _g (Typ.)			
40	0.0038 at V _{GS} = 10 V	33	37.5 nC			
40	0.0045 at V _{GS} = 4.5 V	31	37.3110			

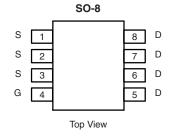
FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET® Gen II Power MOSFET
- 100 % R_a and UIS Tested



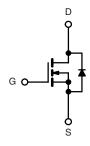
APPLICATIONS

- Secondary Rectification
- · Point of Load



Ordering Information: Si4456DY-T1-E3 (Lead (Pb)-free)

Si4456DY-T1-GE3 (Lead (Pb)-free and Halogen-free)



N-Channel MOSFET

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V_{DS}	40	V	
Gate-Source Voltage		V _{GS}	± 20	¬	
	T _C = 25 °C		33		
Continuous Drain Current (T _J = 150 °C)	T _C = 70 °C	L-	27		
Continuous Diam Current (1) = 150 C)	T _A = 25 °C	I _D	23 ^{b, c}		
	T _A = 70 °C		18 ^{b, c}		
Pulsed Drain Current		I _{DM}	70	A	
Continuous Source-Drain Diode Current	T _C = 25 °C	I.	7.0		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	3.0 ^{b, c}		
Avalanche Current	L = 0.1 mH	I _{AS}	40		
Single Pulse Avalanche Energy		E _{AS}	80	mJ	
	T _C = 25 °C		7.8		
Maximum Power Dissipation	T _C = 70 °C	ь	5.0	14/	
	T _A = 25 °C	P _D	3.5 ^{b, c}	w	
	T _A = 70 °C		2.2 ^{b, c}		
Operating Junction and Storage Temperature I	T _J , T _{stg}	- 55 to 150			

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	29	35	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	13	16	C/VV		

Notes

- a. Based on T_C = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 80 $^{\circ}\text{C/W}.$

Si4456DY

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	-						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	40			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 A		54		1400	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	l _D = 250 μA		- 7		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.5		2.8	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zana Oata Walkana Busin Oamani		V _{DS} = 40 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V, T _J = 55 °C			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
	_	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		0.0031	0.0038	Ω	
Drain-Source On-State Resistance ^a	H _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$		0.0037	0.0045		
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_D = 20 \text{ A}$		110		S	
Dynamic ^b							
Input Capacitance	C _{iss}			5670			
Output Capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		621		pF	
Reverse Transfer Capacitance	C _{rss}			287			
Total Gate Charge	Q _g	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 20 \text{ A}$		81	122	nC	
				37.5	57		
Gate-Source Charge	Q_{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 20 \text{ A}$		17			
Gate-Drain Charge	Q _{qd}			11			
Gate Resistance	R_{g}	f = 1 MHz		1.05	1.6	Ω	
Turn-On Delay Time	t _{d(on)}			145	220		
Rise Time	t _r	V_{DD} = 20 V, R_L = 2 Ω		208	320		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		56	85		
Fall Time	t _f	_		15	23		
Turn-On Delay Time	t _{d(on)}			21	32	ns	
Rise Time	t _r	V_{DD} = 20 V, R_L = 2 Ω		58	90		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		55	85		
Fall Time	t _f	_		8	15		
Drain-Source Body Diode Characterist	ics			•			
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			7	۸	
Pulse Diode Forward Current ^a	I _{SM}				70	Α	
Body Diode Voltage	V_{SD}	I _S = 3 A		0.71	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}			38	60	ns	
Body Diode Reverse Recovery Charge	Q_{rr}	L = 12 A dl/dt = 100 A/up T = 05 °C		42	65	nC	
Reverse Recovery Fall Time	t _a	$I_F = 13 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		21		ns	
Reverse Recovery Rise Time		t _b		17			

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

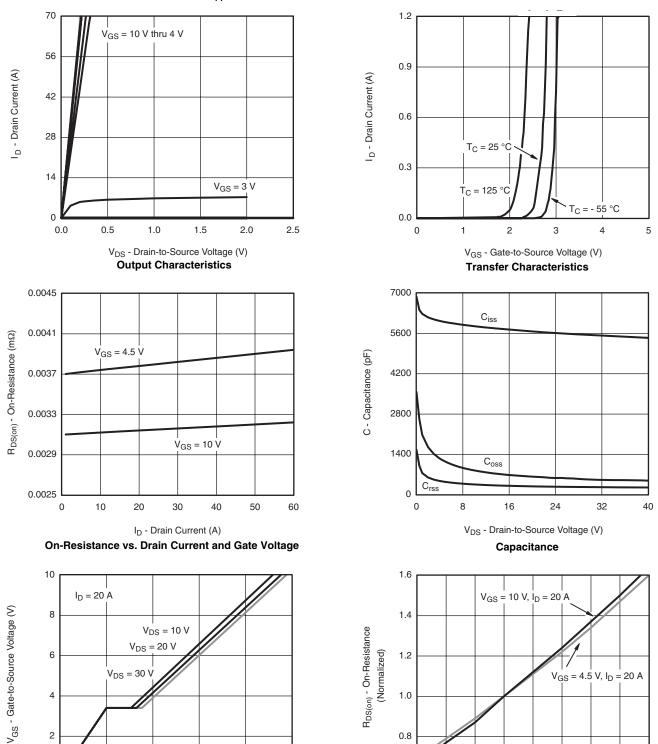
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.







TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted



0.6

- 50

0

0

Q_q - Total Gate Charge (nC)

Gate Charge

125

75

50

T_J - Junction Temperature (°C)

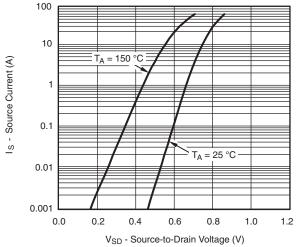
100

150

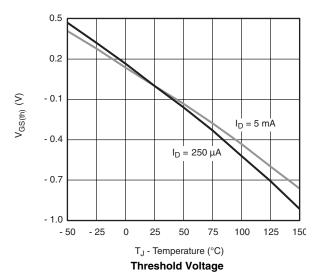
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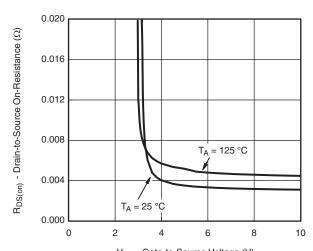
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TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted

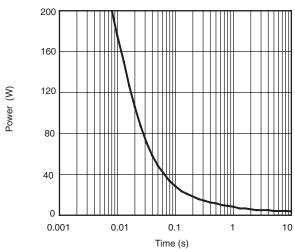


Source-Drain Diode Forward Voltage

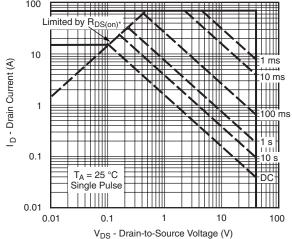




V_{GS} - Gate-to-Source Voltage (V)
On-Resistance vs. Gate-to-Source Voltage

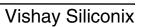


Single Pulse Power, Junction-to-Ambient



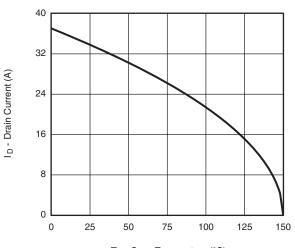
 $V_{DS} \text{ - Drain-to-Source Voltage (V)} \\ \text{* } V_{GS} > \text{minimum } V_{GS} \text{ at which } R_{DS(on)} \text{ is specified} \\$

Safe Operating Area, Junction-to-Ambient



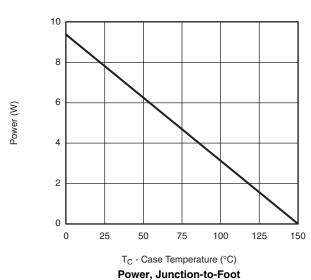


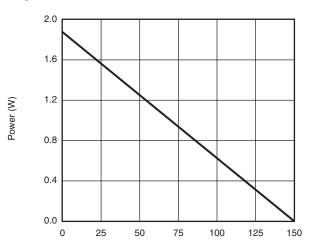
TYPICAL CHARACTERISTICS $T_A = 25 \, ^{\circ}C$, unless otherwise noted



T_C - Case Temperature (°C)

Current Derating*





T_A - Ambient Temperature (°C)

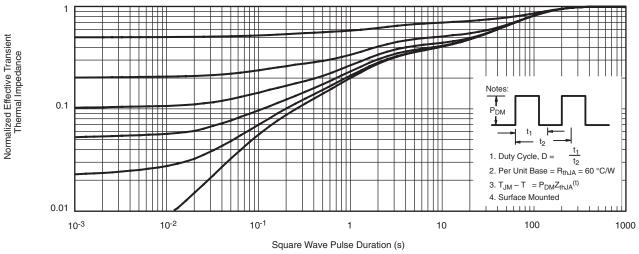
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package

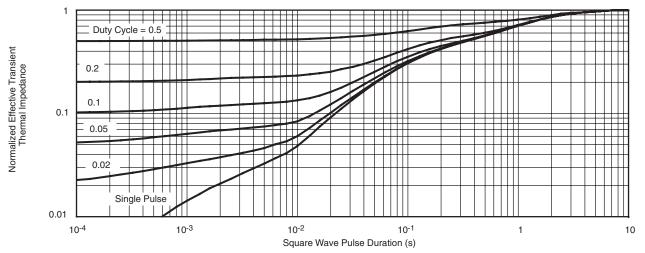
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TYPICAL CHARACTERISTICS $T_A = 25 \, ^{\circ}C$, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIMETERS INCHES			HES	
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
Е	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I. 11-Sep-06					

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RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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